

Report No. APR-25-H0065  
Date: Mar. 19, 2025

# RENESAS SEMICONDUCTOR RELIABILITY REPORT

APPLICATION: High Quality

SERIES: REXFET-1 ANM3

DEVICE: Refer to Product List

Quality Assurance Div.  
Renesas Electronics Corporation

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## Q101 Qualification Test Results

[Note : Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .]

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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### TEST GROUP A – ACCELERATED ENVIRONMENT STRESS TESTS

PC	A1	JESD22-A113 J-STD-020	SMD only; Moisture Preconditioning for HAST/H3TRB,UHAST/AC,TC,IOL/PTC.	3	308	924	0 of 924	-
HAST	A2	JESD22-A110	Ta=130°C, RH=85%, VDSS=Maximum rating, 96h	-	-	-	-	See H3TRB.
H3TRB	A2 alt	JESD22-A101	Ta=85°C, 85%RH, VDSS=Maximum rating, 1,000h	3	77	231	0 of 231	-
UHAST	A3	JESD22-A118 or A101	Ta=130°C, RH=85%, 96h	3	77	231	0 of 231	-
AC	A3 alt	JESD22-A102	Ta=121°C, 100%RH, 96h	-	-	-	-	See UHAST.
TC	A4	JESD22-A104 Appendix 6	Ta=-55°C to 150°C, 1,000cycles	3	77	231	0 of 231	-
TCHT	A4a	JESD22-A104 Appendix 6	TC Hot Test.	-	-	-	-	See TCDT.
TCDT	A4a alt	JESD22-A104 Appendix 6 J-STD-035	TC Delamination Test.	3	77	231	0 of 231	-
IOL	A5	MIL-STD-750 Method 1037	ΔTc=100°C, 15,000cycles	3	77	231	0 of 231	-
PTC	A5 alt	JESD22-A105	Power Temperature Cycling.	-	-	-	-	See IOL.

### TEST GROUP B – ACCELERATED LIFETIME SIMULATION TESTS

HTRB	B1	MIL-STD-750-1 M1039	Tch = 175°C, VDSS=Maximum rating, 1,000h	3	77	231	0 of 231	-
ACBV	B1a	MIL-STD-750-1 M1040 Test condition A	AC blocking voltage.	-	-	-	-	N/A Thyristors Only.
SSOP	B1b	MIL-STD-750-1 M1038 condition B (Zeners)	Steady State Operational.	-	-	-	-	N/A Voltage Regulators (Zeners) Only.
HTGB	B2	JESD22-A108	Tch = 175°C, VGSS=+20V, 1,000h	3	77	231	0 of 231	-

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Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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#### TEST GROUP C – PACKAGE ASSEMBLY INTEGRITY TESTS

DPA	C1	AEC Q101-004 Section4	Random sample of parts that have successfully completed H3TRB or HAST and TC.	3	4	12	0 of 12	-
PD	C2	JEDEC JESD22-B100	Physical Dimensions.	1	30	30	0 of 30	-
WBP	C3	MIL-STD-750-2 Method 2037	Wire Bond Pull.	1bond	10parts	10bonds	0 of 10bonds	-
WBS	C4	AEC Q101-003 JESD22-B116	Wire Bond Shear Test.	1bond	10parts	10bonds	0 of 10bonds	-
DS	C5	MIL-STD-750-2 Method 2017	Die Shear.	1	5	5	0 of 5	-
TS	C6	MIL-STD-750-2 Method 2036	Terminal Strength.	-	-	-	-	N/A SMD
RTS	C7	JESD22-B107	Resistance to Solvents.	-	-	-	-	N/A laser etched parts
RSH	C8	JESD22-A111 (SMD)	Resistance to Solder Heat.	-	-	-	-	N/A Wave solder deprecated.
TR	C9	JESD24-3, 24-4, 24-6 as appropriate	Thermal Resistance.	1	10	10	0 of 10	-
SD	C10	JEDEC J-STD-002	Solderability: (>95% coverage)	3	10	30	0 of 30	-
WG	C11	AEC Q005	see AEC-Q005	-	-	-	Pass	Performed on product TEG with test method based on JESD201.
CA	C12	MIL-STD-750-2 Method 2006	Constant Acceleration.	-	-	-	-	N/A hermetic packaged devices only
VVF	C13	JESD22-B103	Vibration Variable Frequency.	-	-	-	-	N/A hermetic packaged devices only
MS	C14	JESD22-B104	Mechanical Shock.	-	-	-	-	N/A hermetic packaged devices only
HER	C15	JEDEC JESD22-A109	Hermeticity.	-	-	-	-	N/A hermetic packaged devices only

#### TEST GROUP D – DIE FABRICATION RELIABILITY TESTS

DI	D1	AEC Q101-004 Section3	Dielectric Integrity.	1	5	5	0 of 5	Confirmed by process TEG
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Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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**TEST GROUP E – ELECTRICAL VERIFICATION TESTS**

EV	E0	JESD22-B101	External Visual.	All	All	All	0 of All	-
TEST	E1	User/Supplier Specification	Pre and Post Stress Electrical Test.	All	All	All	0 of All	-
PV	E2	Individual AEC user specification	Parametric Verification.	3	25	75	0 of 75	-
ESDH	E3	AEC Q101-001	Electrostatic Discharge, Human Body Model.	1	30	30	0 of 30	HBM:C:100pF,R:1.5K $\Omega$ ,2000V $\uparrow$
ESDC	E4	AEC Q101-005	Electrostatic Discharge, Charged Device Model.	1	30	30	0 of 30	CDM: $\pm$ 1000V $\uparrow$
UIS	E5	AEC Q101-004 Section2	UNCLAMPED INDUCTIVE SWITCHING.	1	5	5	0 of 5	-
SC	E6	AEC Q101-006	Short Circuit Characterization.	-	-	-	-	N/A For smart power parts only.

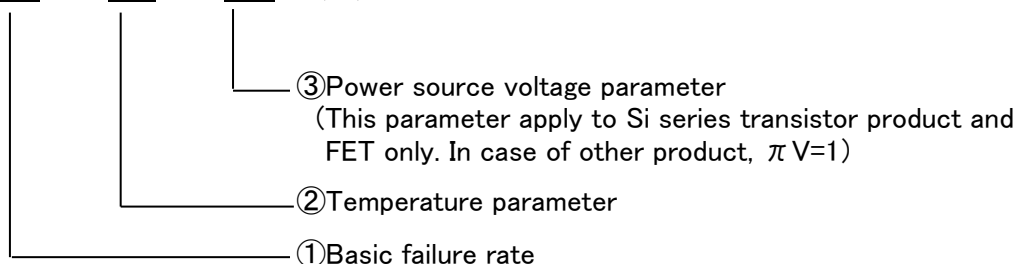
## Calculation method of standard failure

### Calculation method of standard failure rate

Operating reliability is decided by inherent reliability of device and environment condition of use (See below).

### Calculation method of standard failure rate (λ)

$$\lambda = \lambda_b \times \pi T \times \pi V \quad (\text{fit})$$



#### ① Basic failure rate (λ<sub>b</sub>)

Series Name: REXFET-1 ANM3

λ<sub>b</sub> : 0.59 (Fit)

#### ② Temperature parameter (π<sub>T</sub>)

$$\pi T = \exp(11600 \times E_a \times \left( \frac{1}{273 + 55} - \frac{1}{273 + T_a(j)} \right))$$

E<sub>a</sub> : Activation energy

T<sub>j</sub>(T<sub>ch</sub>) : junction temperature

π <sub>T</sub> simplified chart											
E <sub>a</sub> (eV)	T <sub>j</sub> (T <sub>ch</sub> )	40	55	60	65	70	75	80	90	100	110
0.8	π <sub>T</sub>	0.26	1.00	1.53	2.31	3.45	5.08	7.42	15.30	30.37	58.14

#### ③ Power source voltage parameter (π<sub>V</sub>) (Si series transistor products, FET only)

$$S = \frac{\text{supply voltage (VCE or VDS)}}{\text{absolute maximum voltage (VCES or VDSS)}}$$

$$S > 0.2 \quad \pi V = \exp(2.86 \times S - 2.29)$$

$$S \leq 0.2 \quad \pi V = 0.18$$

#### ④ MTTF ( Mean Time To Failure )

MTTF and failure rate have the following relationship in the contingent failure domain

$$\text{MTTF} = \frac{1}{\lambda} \times 10^9 \quad (\text{h})$$

$$\text{MTTF} * = 1,694,915,254 \quad (\text{h})$$

( \* π<sub>T</sub>=1, π<sub>V</sub>=1 )

### Calculation standard

• Confidence level 60% • Standard temperature T<sub>j</sub> = 55°C • Use within recommended conditions

## Product List

[illegible]